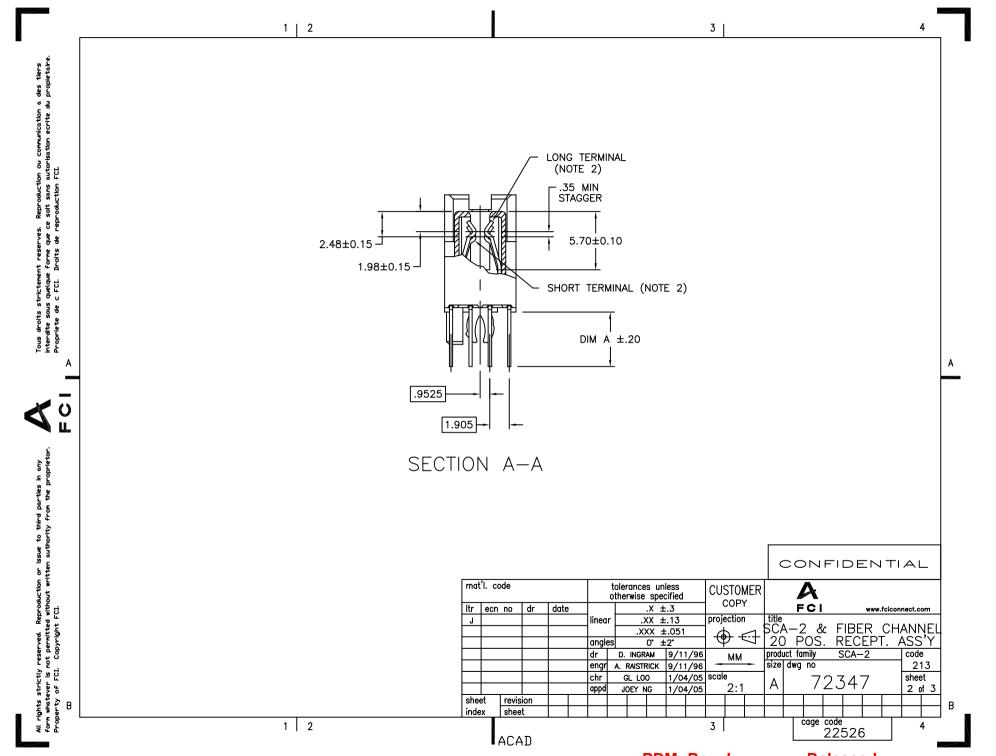


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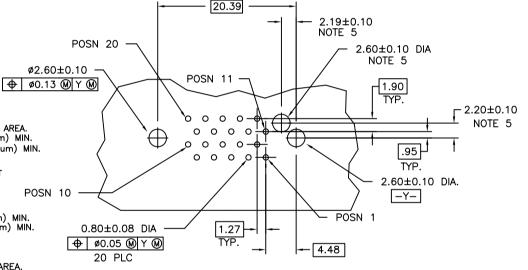
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PRODUCT NUMBER	"A" DIM	POLARIZATION PEG	PLATING	RECOMMEDED P.C. BOARD THICKNESS	PRODUCT NUMBER	PLATING	PRODUCT NUMBER	PLATING	PRODUCT NUMBER	PLATING	
72347-001	2.79	YES	- NOTE ④	1.57mm (0.062")	72347-101		72347-001LF	NOTE ®	72347-101LF		
72347-002	2.79	NO		1.5711111 (0.002)	72347-102	NOTE 6	72347-002LF		72347-102LF		
72347-003	3.18	YES		2.36mm (0.093")	72347-103		72347-003LF		72347-103LF	NOTE (7)	
72347-004	3.18	NO		2.5011111 (0.095)	72347-104		72347-004LF		72347-104LF		
72347-005	4.06	YES		3.18mm (0.125")	72347-105		72347-005LF		72347-105LF		
72347-006	4.06	NO		3.1811111 (0.123)	72347-106		72347-006LF		72347-106LF		
					NOTE	6	NOTE 8	3	NOTE 7	7 —	

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NOTES:

- 1) TRUE POSITION NOTES APPLY AT TERMINAL TIP.
- CONTACTS IN POSITIONS 1 THRU 10 15 & 16 ARE SHORT TERMINALS. CONTACTS IN POSITIONS 11, 12, 13, 14, AND 17, 18, 19, 20 ARE LONG TERMINALS.
- RAW MATERIALS: HOUSING: HTN, UL94V-O, COLOR: BLACK CONTACTS: PHOSPHOR-BRONZE
- CONTACT PLATING: 30u" (0.76um) MIN. GXT PLATING OVER 50u" (1.27um) NICKLE MIN. UNDERPLATE IN CONTACT AREA. 100u" (2.54um) MIN. TIN-LEAD PLATING OVER 50u" (1.27um) MIN. NICKLE UNDERPLATE IN P.C. BOARD LEG AREA. 50u" (1.27um) MIN. NICKLE UNDERPLATE OVER REMAINING AREA.
- DIMENSIONS DO NOT APPLY TO CONNECTOR STYLES WITHOUT POLARIZATION PEG. (SEE CHART)
- CONTACT PLATING: 30µ" (0.76µm) MIN. GOLD PLATING OVER 50µ" (1.27µm) NICKEL MIN. UNDERPLATE IN CONTACT AREA. 100µ" (2.54µm) MIN TIN-LEAD PLATING OVER 50µ" (1.27µm) MIN. NICKEL UNDERPLATE IN P.C. BOARD LEG AREA. 50µ" (1.27µm) MIN. NICKEL UNDERPLATE OVER REMAINING AREA.
- CONTACT PLATING: 30u" (0.76um) GOLD PLATING OVER 50u" (1.27um) NICKLE UNDERPLATE IN CONTACT AREA. 100u" (2.54um) - 200u"(5.08um) TIN PLATING OVER 50u" (1.27um) -100u" (2.54um) NICKEL UNDERPLATE IN P.C. BOARD LEG AREA. 50u" (1.27um) NICKEL UNDERPLATE OVER REMAINING AREA.
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- THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.57MM THICK CIRCUIT BOARD.
- (10) THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.



RECOMMENDED PC BOARD MOUNTING DIMENSIONS COMPONENT SIDE

CONFIDENTIAL

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